

Title (en)

METHOD FOR PACKAGING A SEMICONDUCTOR CHIP CONTAINING SENSORS AND RESULTING PACKAGE

Title (de)

VERFAHREN ZUM EINBAU EINER SENSOREN ENTHALTENEN HALBLEITERSCHEIBE IN EINEM GEHÄUSE, UND GEHÄUSE

Title (fr)

PROCEDE DE MISE EN BOITIER D'UNE PUCE DE SEMI-CONDUCTEUR CONTENANT DES CAPTEURS ET BOITIER OBTENU

Publication

EP 1208605 A1 20020529 (FR)

Application

EP 00958732 A 20000824

Priority

- FR 0002367 W 20000824
- FR 9911024 A 19990902

Abstract (en)

[origin: FR2798226A1] The invention concerns a method for producing a package (30) for a semiconductor chip comprising a semiconductor chip (20) comprising one or several bond pads on the top surface for providing terminals for one or several sensors (22) in the upper surface and a chip carrier (32) comprising an opening (34) and one or several external terminals. The semiconductor chip (20) upper surface is fixed to the chip carrier (32) lower surface such that the sensor(s) (22) are arranged beneath the first opening (34) and an interface zone (40) is formed, wherein the semiconductor chip (20) upper surface extends beyond the first opening (34) in the chip carrier (32) and each bond pad is coupled to a portion of the external terminals exposed at the chip carrier (32) lower surface for example with weld points (42). A sealing ring (44, 46) encapsulates the interface zone (40) and a coating material (48) encapsulates the chip carrier (32) lower surface and a lower surface of the semiconductor chip (20).

IPC 1-7

H01L 31/0203; **H01L 33/00**

IPC 8 full level

H01L 23/31 (2006.01)

CPC (source: EP US)

H01L 23/3107 (2013.01 - EP US); **H01L 2224/32245** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/73265** (2013.01 - EP US); **H01L 2224/92247** (2013.01 - EP US)

Citation (search report)

See references of WO 0117033A1

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

FR 2798226 A1 20010309; **FR 2798226 B1 20020405**; EP 1208605 A1 20020529; US 6825551 B1 20041130; WO 0117033 A1 20010308

DOCDB simple family (application)

FR 9911024 A 19990902; EP 00958732 A 20000824; FR 0002367 W 20000824; US 7008002 A 20020701